

ByungJun Kim

Master's course
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EDUCATION

Aug. 2023 ~ Present	Sungkyunkwan University 반도체융합공학과 <i>Ph.D. Student</i>	Suwon, Korea
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RESEARCH INTERESTS

- Semiconductor package
- Semiconductor chip bonding
- Synthesis of polymer
- Self-healable devices
- Solder Bumping

RESEARCH EXPERIENCES

- Research Student at MSPL, Sungkyunkwan University, Korea (Sep. 2023 ~ Present) /
Development of chip bonding process